

EAST Search History

Ref #	hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	250	"Mold3 near5 apparatus and substrate and (stiffener or dam)	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/04/03 18:59
S2	81	438/120.col1s.	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/04/03 19:00
S3	395	257/667.col1s.	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/04/03 19:00
S4	394	257/671.col1s.	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/04/03 19:00
S5	315	257/678.col1s.	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/04/03 19:29
S6	3107	257/678.col1s.	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/04/03 19:29
S7	19	{257/e23.001}.col1s.	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/04/03 19:30
S8	84	{257/e23.18}.col1s.	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/04/03 19:30
S9	11495	{257/e23.039}.col1s.	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/04/03 19:30
S10	259	Mold3 near5 apparatus and substrate and (stiffener or dam)	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/08/08 16:50
S11	39	458/120.col1s.	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/08/08 16:50
S12	595	257/667.col1s.	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/08/08 16:50
S13	3993	257/678.col1s.	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/08/08 16:50
S14	3247	257/678.col1s.	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/08/08 16:50
S15	3155	257/678.col1s.	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/08/08 16:50
S16	30	{257/e23.001}.col1s.	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/08/08 16:50
S17	35	{257/e23.18}.col1s.	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/08/08 16:50
S18	1355	{257/e23.039}.col1s.	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/08/08 16:50
S19	32	{4891687}*{5929517}*{5973389}*{6020221}*{6279158}*{6284569}*{6303985}*{6326544}*{6426565}*{6440777}*{6486562}*{6517662}*{6519843}*{6539385}*{6724071}.PN.	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/08/08 16:51
S20	2	{4710419}.PN.	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/08/08 17:23
S21	2	{3650593}.PN.	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/08/08 17:23
S22	315	ppray33 near3 mold3	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/08/08 17:33
S23	260	S22 and semiconductor and substrate	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/08/08 17:32
S24	262	Mold3 near5 apparatus and substrate and (stiffener or dam)	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/10/12 14:18
S25	39	458/120.col1s.	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/10/12 14:18
S26	397	257/667.col1s.	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/10/12 14:18
S27	4021	257/678.col1s.	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/10/12 14:18
S28	3330	257/678.col1s.	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/10/12 14:18
S29	336	257/678.col1s.	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/10/12 14:18
S30	39	{257/e23.001}.col1s.	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/10/12 14:18
S31	39	{257/e23.18}.col1s.	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/10/12 14:18
S32	1569	{257/e23.039}.col1s.	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/10/12 14:18
S33	260	Mold3 near5 apparatus and substrate and (stiffener or dam)	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/10/12 14:18
S34	39	438/120.col1s.	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/10/12 14:18
S35	397	257/667.col1s.	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/10/12 14:18
S36	4021	257/678.col1s.	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/10/12 14:18
S37	3330	257/678.col1s.	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/10/12 14:18
S38	3316	257/678.col1s.	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/10/12 14:18
S39	39	{257/e23.001}.col1s.	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/10/12 14:18
S40	39	{257/e23.18}.col1s.	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/10/12 14:18
S41	1569	{257/e23.039}.col1s.	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/10/12 14:18
S42	32	{4891687}*{5929517}*{5973389}*{6020221}*{6279158}*{6284569}*{6303985}*{6326544}*{6426565}*{6440777}*{6486562}*{6517662}*{6519843}*{6539385}*{6724071}.PN.	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/10/12 14:18
S43	3	{4710419}.PN.	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/10/12 14:18
S44	3	{3650593}.PN.	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/10/12 14:18
S45	3082	ppray33 near3 mold3	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/10/12 14:18
S46	375	S22 and semiconductor and substrate	US-PGPUB; USPAT; EPO; JPO; DEMENT; IBM_TDB	OR	ON	2007/10/12 14:18

10/12/07 3:26:08 PM

C:\Documents and Settings\vtrinh\My Documents\EAST\workspaces\10077554.wsp